Features

- Low profile surface mount package
- Glass Passivated Chip Junction
- High temperature soldering 250℃/10second at terminals
- RoHS Compliant
- Halogen & Lead Free

SOD-123FL

特征

- 薄型表面贴装封装
- 玻璃钝化芯片结
- 端子高温焊接 250℃/10 秒
- 符合 RoHS 标准
- 无卤无铅

Device Type 器件型号	Device Marking 器件印字
SM4007PL-CN	A7

MECHANICAL DATA 器件数据

- Case: SOD-123FL　壳体：SOD-123FL
- Terminals:　Solderable Per MIL-STD-750, Method 2026
  接触端：可根据 MIL-STD-750，方法 2026 进行焊接

Application 应用

- General purpose rectification of power supplies 电源通用整流
- Inverters 逆变器
- Converters 转换器
- Freewheeling diodes for consumer and telecommunication
  消费类产品和电通信用续流二极管

ORDERING INFORMATION
订购信息

Device Type 器件型号	Package 封装	Reel Size 卷盘尺寸	SPQ 标准包装量	MPQ 最小包装数量	MOQ 最小订购数量
SM4007PL-CN	SOD-123FL	7 Inch 英寸	3000/Reel 卷	45000/Box 盒	180000/Carton 箱

Maximum Ratings (T_A= 25°C unless otherwise noted)

最大额定值(如无另外标识，环境温度=25°C)

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.
单相半波 60 Hz，电阻或电感负载，电容负载电流减额 20%

Parameter 参数	Symbol 符号	Note	SM4007PL-CN	Unit 单位
Maximum repetitive peak reverse voltage 最大重复峰值反向电压	V_{RRM}	/	1000	V
Maximum RMS Voltage 最大反向有效电压	V_{RMS}	/	700	V
Maximum DC Blocking Voltage 最大直流截止电压	V_{DC}	/	1000	V
Maximum Average Forward Rectified Current 最大正向平均整流电流	$I_{(AV)}$	T_L=100°C	1.0	A
Peak Forward Surge Current 峰值正向浪涌电流	I_{FSM}	8.3ms single half sine-wave	35	A
Typical Junction Capacitance 典型结电容	C_j	1MHz V_{DC}=4.0	18	pF
Maximum Instantaneous Forward Voltage @1.0A 最大瞬时正向电压 @1.0A	V_F	/	1.1	V
Maximum DC Reverse Current rated DC Blocking Voltage per element 在额定直流截止电压下的 最大直流反向电流	I_R	T_A=25℃	5.0	μA
		T_A=125℃	500	
Operating Junction Temperature 工作结点温度	T_J	/	-55 to +150	℃
Storage Temperature Range 储存温度范围	T_{STG}	/	-55 to +150	℃
Typical Thermal Resistance 典型热阻	$R_{\theta JA}$	/	85	℃/W

Characteristic Diagram

特性图

FIG. 1 - DERATING CURVE OUTPUT RECTIFIED CURRENT

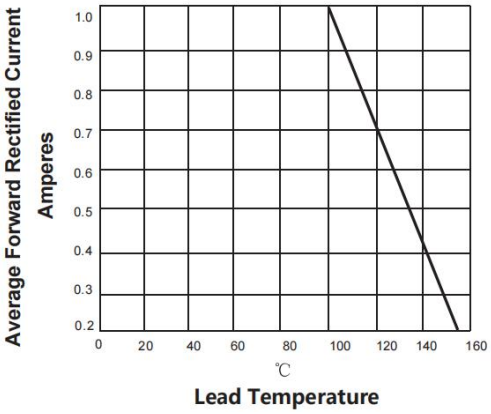


FIG. 2 - MAXIMUM NON- REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

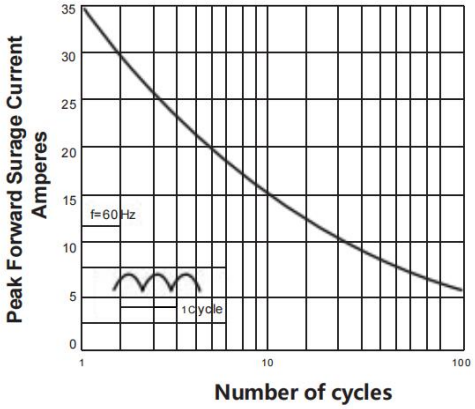


FIG. 3 - TYPICAL FORWARD VOLTAGE CHARACTERISTICS

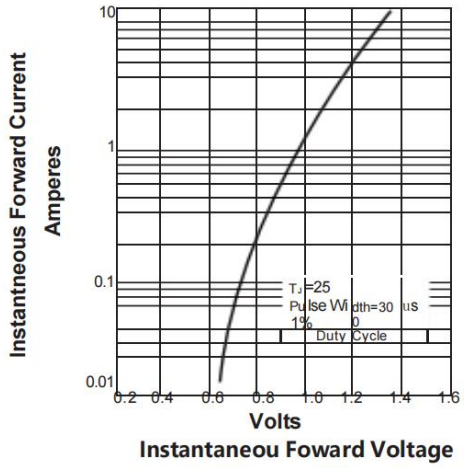
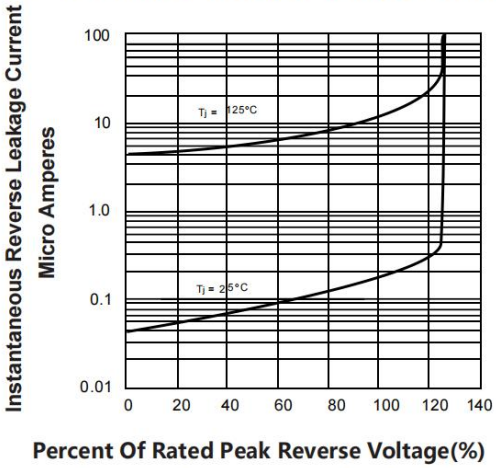
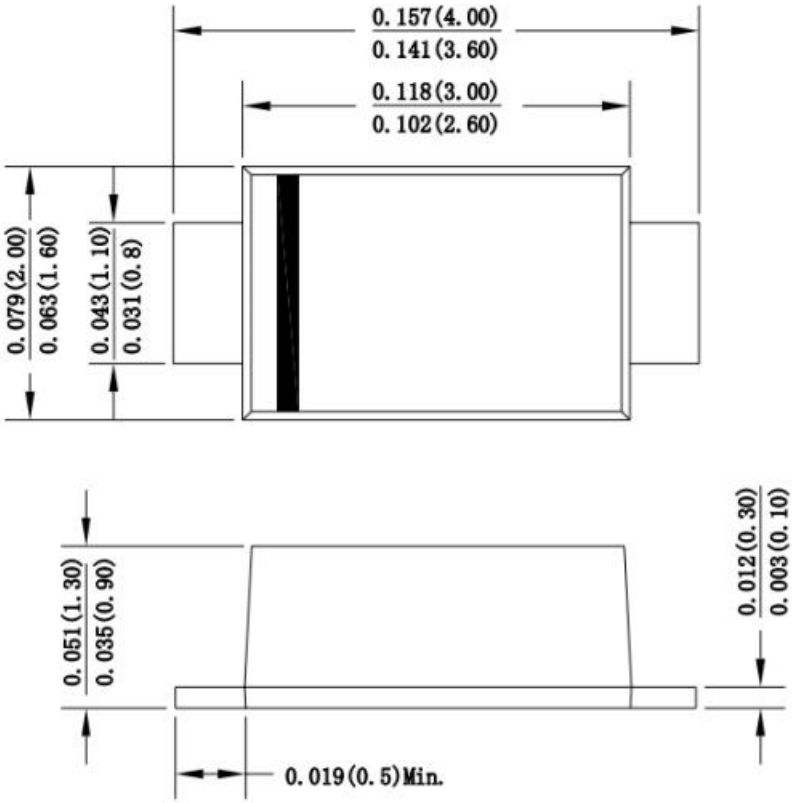


FIG. 4 - TYPICAL REVERSE LEAKAGE CHARACTERISTICS



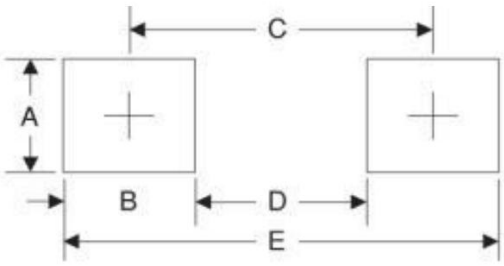
Package 封装信息

SOD-123FL



Suggested Pad Layout

焊盘布局参考



Symbol	Unit (mm)	Unit (inch)
A	1.2	0.048
B	1.15	0.045
C	3.10	0.122
D	1.95	0.077
E	4.25	0.167

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